

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claims 81 and 85 as follows:

Listing of Claims:

1-80. (Cancelled)

81. (Currently Amended) A method of [electrically ]conductively isolating modules within an integrated circuit package assembly, comprising:

attaching a first and second module to a substrate having a first and opposing second side;

providing a first conductive surface having a first and opposing second side abutting the opposing second side of the substrate;

providing a dielectric layer having a first and opposing second side abutting the opposing second side of the first conductive surface;

providing a second conductive surface abutting the opposing second side of the dielectric;

conductively coupling the first conductive surface to a ground plane of the first module; and

conductively coupling the second conductive surface to a ground plane of the second module.

82. (Previously Presented) The method of claim 81, further comprising encasing the assembly in a polymer.

83. (Previously Presented) The method of claim 81, further comprising encasing the assembly in a ceramic.

84. (Previously Presented) The method of claim 81, further comprising encasing the assembly in glass.

85. (Currently Amended) A method of [electrically] conductively isolating modules within an integrated circuit package assembly, comprising:

forming a capacitor within the semiconductor package assembly, the capacitor having a first terminal and a second terminal;

coupling a ground plane of a first module to the first terminal of the capacitor; and

coupling a ground plane of a second module to the second terminal of the capacitor.

86-89. (Cancelled)

90. (Previously Presented) The method of claim 85, wherein the assembly further comprises a substrate having a first side and an opposing second side, and wherein forming a capacitor within the semiconductor package assembly further comprises forming the capacitor adjacent to the first side, and attaching the first and second modules to the first side.

91. (Previously Presented) The method of claim 85, wherein the assembly further comprises a substrate having a first side and an opposing second side, and wherein forming a capacitor within the semiconductor package assembly further comprises forming the capacitor adjacent to the first side, and attaching the first and second modules to the second side.

92. (Previously Presented) The method of claim 85, wherein the assembly further comprises a substrate and the modules have first and opposing second sides, and further wherein forming the capacitor within the semiconductor package assembly comprises forming the capacitor proximate to the opposing second sides of the modules.

93. (Previously Presented) The method of claim 85, wherein the assembly further comprises a first and a second substrate, the first module being attached to the first

substrate and the second module being attached to the second substrate, and wherein forming the capacitor within the semiconductor package assembly further comprises forming the capacitor between the first module and the second module.